501796175 01/24/2012

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Lee-Chung LU	01/06/2012
Li-Chun TIEN	01/05/2012
Hui-Zhong ZHUANG	01/05/2012
Mei-Hui HUANG	01/04/2012

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park	
City:	Hsinchu	
State/Country:	TAIWAN	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13267310

CORRESPONDENCE DATA

 Fax Number:
 (703)518-5499

 Phone:
 7036841111

 Email:
 tsmc@ipfirm.com

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via

US Mail.

Correspondent Name: Lowe Hauptman Ham & Berner, LLP (TSMC)

Address Line 1: 1700 Diagonal Road, Suite 300 Address Line 4: Alexandria, VIRGINIA 22314

ATTORNEY DOCKET NUMBER: T5057-R521

NAME OF SUBMITTER: Randy A. Noranbrock

Total Attachments: 1

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PATENT REEL: 027584 FRAME: 0336 OP \$40.00 13267310

501796175

ASSIGNMENT

	In consideration of the premises and other	good and valuable co	onsideration in hand paid,	the receipt and sufficiency of
which is	hereby acknowledged, the undersigned		• 1	1

1) Lee-Chung LU

4) Mei-Hui HUANG

- 2) Li-Chun TIEN
- 3) Hui-Zhong ZHUANG

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at No.

8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

INTEGRATED CIRCUITS AND METHODS OF DESIGNING THE SAME

- (a) for which an application for United States Letters Patent was filed on October 6, 2011, and identified by United States Patent Application No. 13/267, 310; or
- (b) for which an application for United States Letters Patent was executed on

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Lee Chung In
Name: Lee-Chung LU

Name: Li-Chun TIEN

3) Hui - Zhong ZHUAUG Name: Hui-Zhong ZHUANG

1/6/2012

Date:

Vr. 20/2

Date:

01/05/2012 Date:

01/04/2012

Date:

PATENT REEL: 027584 FRAME: 0337

RECORDED: 01/24/2012